

Q1
an outside frame formed with positioning holes,
said tie bar being connected to said outside frame; and

a deformable portion included in said tie bar for
preventing said outside frame from deforming under
extraneous physical stress.--

Q2
--5. (amended) A frame comprising a combination
of lead frames arranged such that element loading portions
to be loaded with semiconductor elements thereof are
positioned one above the other, said lead frames each
comprising:

a tie bar to which the element loading portions
are connected by lead forming portions;

an outside frame formed with positioning holes,
said tie bar being connected to said outside frame; and

a deformable portion included in said tie bar for
preventing said outside frame from deforming under physical
stress.--

Q3
--12. (amended) The semiconductor device as
claimed in claim 11, wherein the leads are positioned on an
extension of a bottom of said seal resin so that a bottom
surface of said leads and a bottom surface of said seal
resin are coplanar.--
